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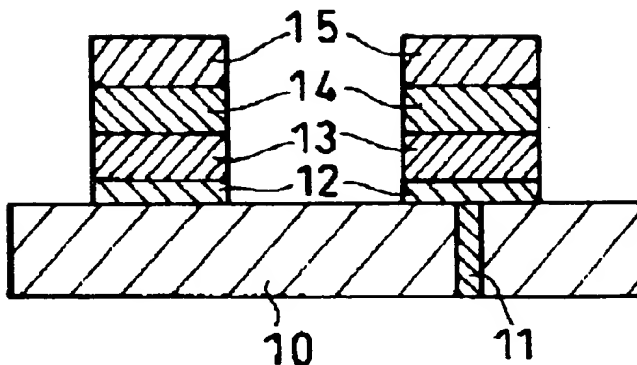
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TITLE : THIN-FILM CAPACITOR AND  
 FABRICATION THEREOF



**ABSTRACT :** **PROBLEM TO BE SOLVED:** To improve adhesion of a substrate to an underlying electrode layer by having interposed an adhesion layer of a metal oxide composing the underlying electrode layer between the substrate and underlying electrode layer.

**SOLUTION:** In order to improve adhesion of a substrate 10 forming a thin-film capacitor to the underlying electrode layer 13 forming a capacitor, the oxide layer of the same material as the underlying electrode layer 13 is introduced between. More specifically, in a thin-film capacitor formed on a mica substrate, an adhesion layer 12 of RuO<sub>2</sub> is formed between the underlying electrode layer 13 of Ru and the substrate 10. In contrast, when the underlying electrode layer 13 comprises Ir, an adhesion layer 12 of IrO<sub>2</sub> is formed between the substrate 10 and the underlying electrode layer 13. The degree of oxidation of the adhesion layer 12 is decreased continuously, starting from the substrate 10 toward the underlying electrode layer 13.

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